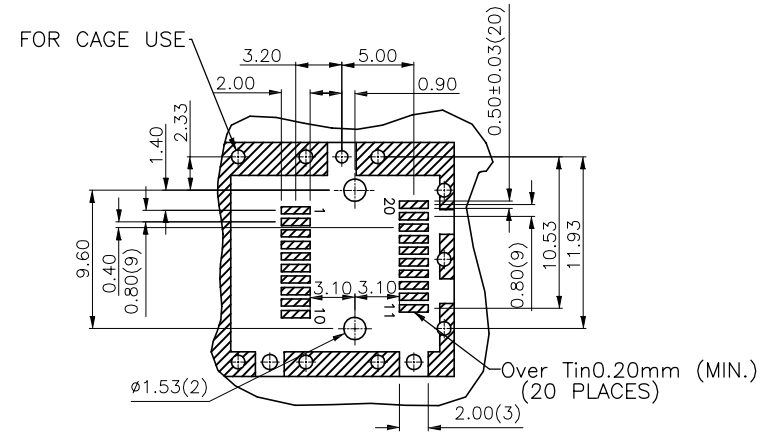
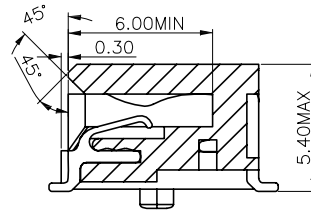
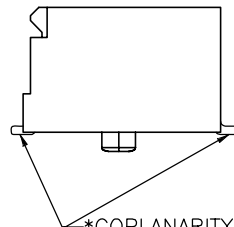
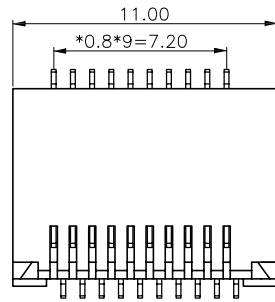


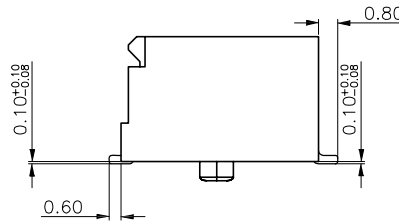
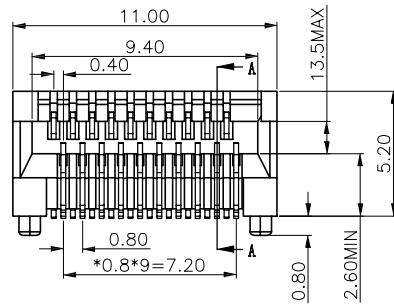
REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD



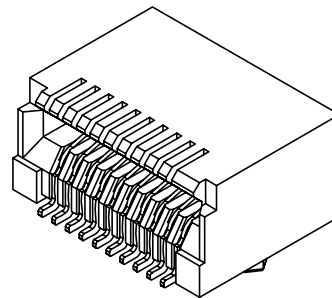
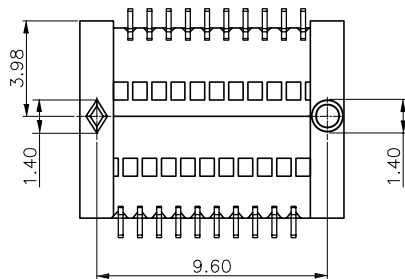
PCB LAYOUT (CONNECTOR) / TOP VIEW

- NOTE:
- MECHANICAL:
- CONNECTOR MATERIAL:
- 1.HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0.
 - 2.CONTACT: PHOSPHOR BRONZE THICKNESS=0.20mm.
 - 3.PLATING: GOLD PLATING OVER NICKEL
 - 4.DURABILITY:250 CYCLES MIN.
- ELECTRICAL:
- 1.VOLTAGE RATING : 30 VAC RMS MAX.
 - 2.CURRENT RATING : 0.5 AMP MAX.
 - 3.DIFFERENTIAL IMPEDANCE : 100 Ohms.
 - 4.CAPACITANCE:1.2pF MAX.
 - 5.CONTACT RESISTANCE: 20 MILLIOHMS MAX.
 - 6.INSULATION RESISTANCE: 500 MEGAOHMS MIN.
 - 7.TEMPERATURE:
 - SOLDER TEMPERATURE SUGGEST 250°C~270°C.(5 - 10 sec)
 - OPERATING:-40°C to +85°C
 - STORAGE:-40°C to +85°C
- PART NUMBER : SFP-008X-L

GOLD PLATED:
 1- 3u' 2- 6u' 3-15u'
 4-30u' 5-50u'



SECTION A-A



MM (INCH)		DRFT: JDM	DATE: 08/15/06	Xmultiple Technologies, Inc.	
TOLERANCES EXCEPT AS NOTED		CHKD:	DATE:		
.0 ± 0.20		MFD:	DATE:	TITLE SFP CONNECTOR 20PIN	
.00 ± 0.15		APPVL:	DATE:		
.000 ± 0.075		MATERIAL:		DRAWING NO. SFP-008 /PART NO. SEE NOTE	
ANGLES ±		QT'Y :			
THIRD ANGLE PROJECTION		FINISH:		DO NOT SCALE DRAWING	
		SCALE :		SHEET X OF Y	